

No.	Item	Description	Data and Model
1	FPC Main material	Brand	taiflex、 graceth) 、 SY
2	PCB Material	Brand	SY、 ITEQ、 KB
3	Texture	Texture Brand	PI、 PET
4	Cover Film	Brand	taiflex、 graceth、 SY
5	Max Layers	LAYER	1-14layers (sample) 、 1-12layers(manufacture)
6	Finish Board thickness	mm	0.25-6.0mm(samplel) Rigid - Flex PCB 0.25-6.0mm
7	Min Pattern Width / Spacing	mm	0.05mm/0.05mm
8	Max finish board size	mm	230*450mm
9	Finish Board thickness tolerance	mm	±50.05mm
10	PP Thickness	um	12.5um 、 25um 、 50um
11	Copper thickness	um	12um 、 18um 、 36um 、 70um
12	Stiffener materail	Variety	FR4/PI/PET/SUS/PSA
13	Surface treatment	Variety	ENIG、 Immersion tin、 OSP、 immersion silver、 plating gold
14	Min hole size	mm	Mechanical Hole : 0.15mm 、 Laser Hole0.1mm
15	Hole tolerance	mm	NPTH:±0.05mm 、 PTH:±0.075mm
16	Cover film color	Variety	Yellow 、 Black
17	PI thickness	mil	0.5mil、 0.7mil、 0.8mil、 1mil、 2mil
18	Max number of layers of FPCB		1-8layers
19	Min finished size	mm	5mm*8mm

20	Min pad	mm	inner layer (5mil) 、 outer layer (4mil)
21	Stiffener min size	mm	4mm×5mm
22	Stiffener max size	mm	32mm×32mm
23	Stiffener alignment accuracy	mm	±0.075mm
24	Cover minimum opening size	mm	0.6×0.6mm(steeling tooling)、 0.5×0.5mm(Precision tooling)
25	Minimum opening spacing for covering film	mm	0.5mm(Precision tooling)、 0.2mm (Laser Routing) 、 0.15mm(Normal drilling)
26	Coating film overflow amount (unilateral)	mm	Normal0.08-0.12mm 、 Limitation0.03mm
27	Min diameter of gold finger semicircle hole	mm	0.25mm , Normal value0.3mm
28	Rigid-Flex PCB : Peel-off strength	N	1.4N
29	Rigid-Flex PCB : Planeness	um	Less than 15um before baking; less than 30um after baking
30	Rigid-Flex PCB : thermal shock	°C	288°C (3 times within 10 seconds)
31	Rigid-Flex PCB : W/B gold wire pull	g	> 6g
32	Rigid-Flex PCB : min.board thickness	mm	FPCB 0.1mm、 4Layers 0.3mm、 6Layers 0.5mm、 8Layers 0.6mm、 10Layers0.8mm